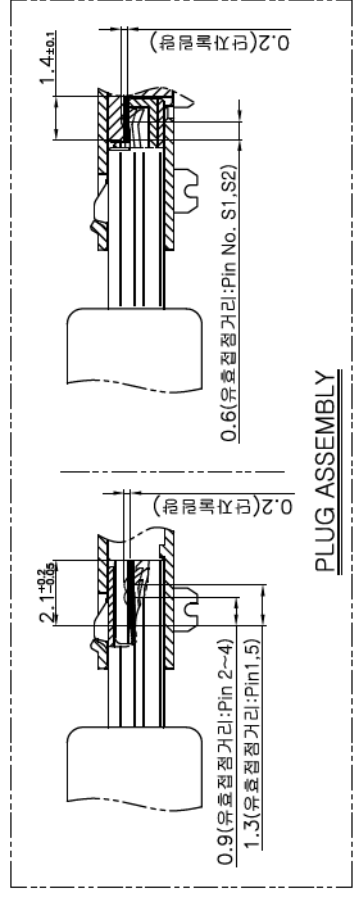
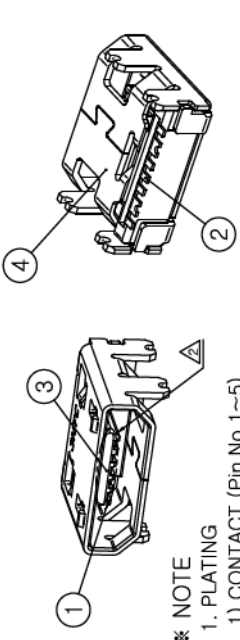


Rev No.	Description of Revision	Date	Name	Approved	ECN No.
△X1	도금 사양 변경 (고객 요청)	2012.12.14	H.H.KIM		-
△X1	형상 변경 (소스 변경)	2013.02.28	B.W.Na		-



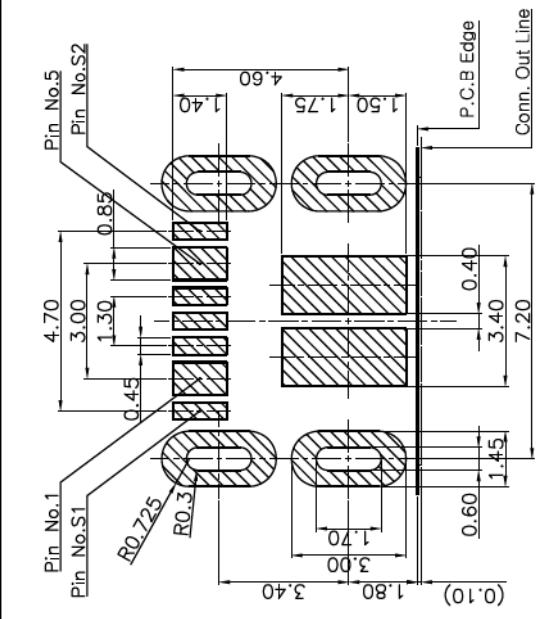
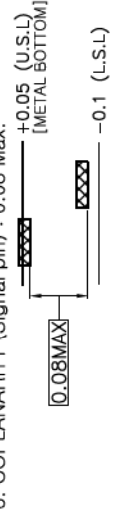
PLUG ASSEMBLY



※ NOTE

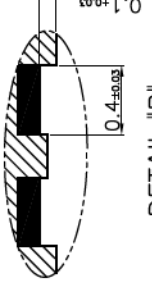
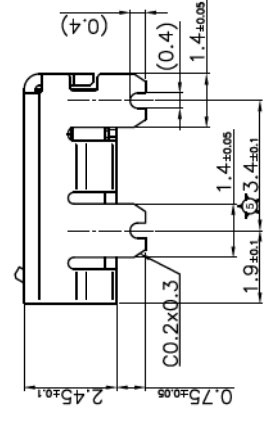
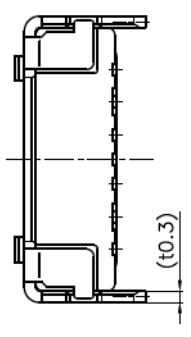
- 1) PLATING
 1) CONTACT (Pin No.1~5)
 △ - Contact Area : Au 0.05 μ m Min. over Pd-Ni 1.0 μ m Min. over Plating Ni 2.0~5.0 μ m.(Brush Plating)
 - Lead Area : Au 0.05 μ m Min. over Ni 0.2~3.0 μ m.(Jig Plating)
- 2) CONTACT (Pin No.S1, S2)
 - Contact Area : Au 0.05 μ m Min. over Ni 2.0~5.0 μ m.(Brush Plating)
 - Lead Area : Au 0.05 μ m Min. over Ni 0.2~3.0 μ m.(Jig Plating)
- 3) METAL SHELL (Dipping Plating)
 - Sn 1.0~3.0 μ m over Ni 0.2~3.0 μ m.(Reflow Finish)
- 4) GUARD PLATE : Cleansing

2. ☆ : C.T.Q
3. COPLANARITY (Signal pin) : 0.08 Max.

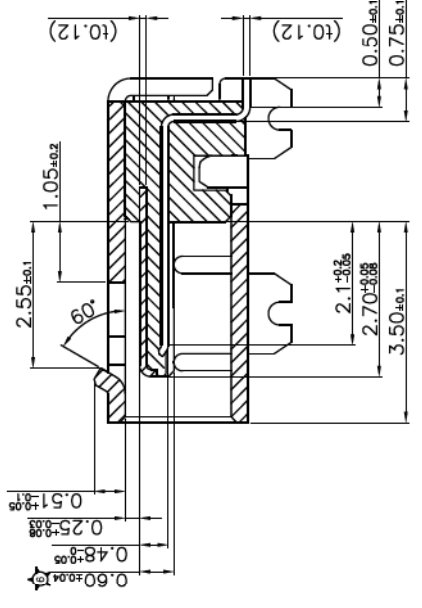


P.C.B LAYOUT

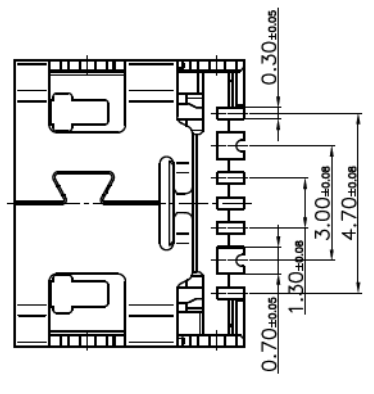
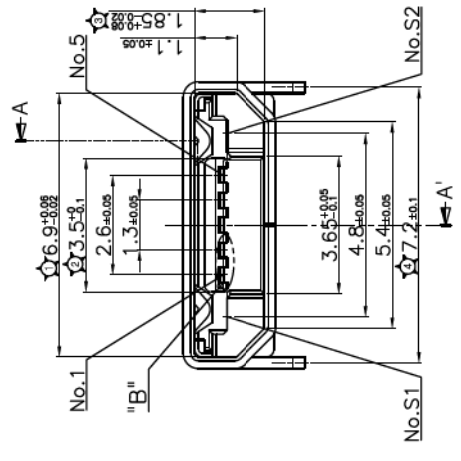
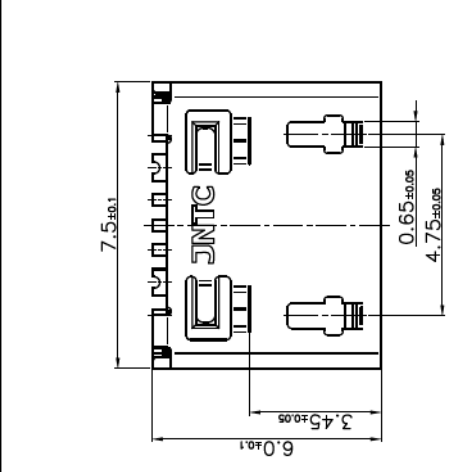
General Tolerance : ± 0.05



DETAIL "B"



SECTION A-A'



4	METAL SHELL	STSS304	Note. 1	10.3
3	GUARD PLATE	STSS301	Cleansing	10.12
2	CONTACT	C7025	Note. 1	10.12
1	HOUSING	LCP	Black Color	UL94V-0
No	Descriptions	Material	Finish	Remarks
General Tolerance		Scale	N/S	Units
Dimension		mm (*)	Date	2012. 10. 17
X	± 0.2	Drawn	Design	Checked
X.X	± 0.1	M. Y. LEE		Reviewed
X.XX	± 0.05			Approved
X.XXX	± 0.01			1 of 1
ANGLE	$\pm 1^\circ$			HY07-AB1700
				MMI-7P (USB) Socket
				Customer Drawing
				Rev.
				2